

RECEIVED
CENTRAL FAX CENTER
APR 23 2007

U.S. Patent Application Serial No. 10/607,514
Amendment dated April 23, 2007
Response to Official Action dated January 23, 2007

Amendments to the Claims:

The following listing of claims replaces all prior versions and listings of the claims in this application.

Listing of the Claims:

1. - 28. (Cancelled).

29. (Previously Presented) A radiation cured encapsulating material having a tear resistance of less than about 2.20 pounds force, an adhesion force to an underlying surface material of greater than about 0.0044 pounds force, and a Young's modulus at 25°C in the range of from about 3000 to about 15,000 psi.

30. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 5%.

31. (Previously Presented) A radiation cured encapsulating material as defined by claim 30, having a tear resistance of less than about 1.10 pounds force, a percent elongation at break of at least about 10%, and an adhesion force to an underlying surface material of greater than about 0.011 pounds force.

32. (Previously Presented) A radiation cured encapsulating material as defined by claim 30, having a tear resistance of less than about 0.44 pounds force, a percent elongation at break of at least about 20%, and an adhesion force to an underlying surface material of greater than about 0.015 pounds force.

U.S. Patent Application Serial No. 10/607,514
Amendment dated April 23, 2007
Response to Official Action dated January 23, 2007

33. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, formed by radiation curing a composition comprising from about 30 to about 80 weight percent of a polyether-based urethane acrylate oligomer, from about 1 to about 40 weight percent of isocyanurate monomer having a plurality of acrylate or methacrylate groups, and an effective amount of a photoinitiator for radiation curing the composition upon exposure to curing radiation.

34. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the polyether-based urethane acrylate oligomer comprises a polypropylene glycol-based urethane acrylate oligomer.

35. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the isocyanurate monomer comprises a triacrylate of trishydroxyethyl isocyanurate.

36. (Currently Amended) A radiation cured encapsulating material ~~as defined by claim 33~~, having a tear resistance of less than about 2.20 pounds force, an adhesion force to an underlying surface material of greater than about 0.0044 pounds force, and a Young's modulus at 25°C in the range of from about 3000 to about 15,000 psi, formed by radiation curing a composition comprising from about 40 to about 75 weight percent of the polyether-based urethane acrylate oligomer, from about 10 to about 30 weight percent of the isocyanurate monomer having a plurality of acrylate or methacrylate groups, and from about 0.1 to about 20 weight percent of the photoinitiator for radiation curing the composition upon exposure to curing radiation.

U.S. Patent Application Serial No. 10/607,514
Amendment dated April 23, 2007
Response to Official Action dated January 23, 2007

37. (Currently Amended) A radiation cured encapsulating material ~~as defined by claim 33,~~ having a tear resistance of less than about 2.20 pounds force, an adhesion force to an underlying surface material of greater than about 0.0044 pounds force, and a Young's modulus at 25°C in the range of from about 3000 to about 15,000 psi, formed by radiation curing a composition comprising from about 50 to about ~~75~~ 70 weight percent of the polyether-based urethane acrylate oligomer, from about 15 to about ~~30~~ 25 weight percent of the isocyanurate monomer having a plurality of acrylate or methacrylate groups, and from about 1 to about 10 weight percent of the photoinitiator for radiation curing the composition upon exposure to curing radiation.

38. (Previously Presented) A radiation cured encapsulating material as defined by claim 37, wherein the polyether-based urethane acrylate oligomer comprises a polypropylene glycol-based urethane acrylate oligomer and the isocyanurate monomer comprises a triacrylate of trishydroxyethyl isocyanurate.

39. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 1.10 pounds force.

40. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 0.44 pounds force.

41. - 43. (Cancelled).

44. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 5%.

U.S. Patent Application Serial No. 10/607,514
Amendment dated April 23, 2007
Response to Official Action dated January 23, 2007

45. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 10%.

46. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 20%.

47. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 1.10 pounds force and a percent elongation at break of at least about 10%.

48. (Previously Presented) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 0.44 pounds force and a percent elongation at break of at least about 20%.

49. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the composition further comprises a viscosity-reducing component in an amount sufficient to lower the viscosity of the composition.

50. (Previously Presented) A radiation cured encapsulating material as defined by claim 33, wherein the composition further comprises a coefficient of friction reducing component in an amount sufficient to lower the coefficient of friction of the radiation cured material.

51. - 52. (Cancelled).

U.S. Patent Application Serial No. 10/607,514
Amendment dated April 23, 2007
Response to Official Action dated January 23, 2007

53. (New) A radiation cured encapsulating material as defined by claim 33, formed by radiation curing a composition comprising from about 50 to about 80 weight % of a polyether-based urethane acrylate oligomer, from about 15 to about 40 weight % of isocyanurate monomer having a plurality of acrylate or methacrylate groups, and from about 1 to about 10 weight % of photoinitiator for radiation curing the composition upon exposure to curing radiation.